

## Description

The IS280-4x series combine two AlGaAs infrared emitting diodes as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic SO16 package.

With the robust coplanar double mold structure, IS280-4x series provide the most stable isolation feature.

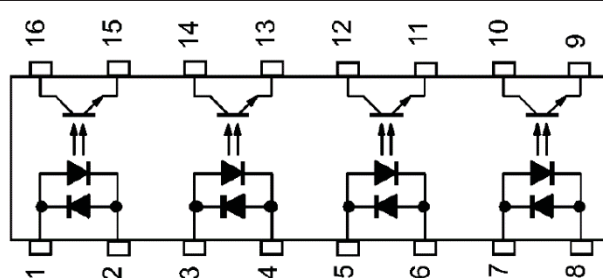
## Features

- High isolation 3750 VRMS
  - CTR flexibility available see order information
  - AC input with transistor output
  - Operating temperature range - 55 °C to 110 °C
  - REACH compliance
  - Halogen free
  - MSL class 1
  - Regulatory Approvals
    - UL - UL1577
    - VDE - EN60747-5-5(VDE0884-5)
    - CQC - GB4943.1, GB8898
    - cUL- CSA Component Acceptance
- Service Notice No. 5A

## Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

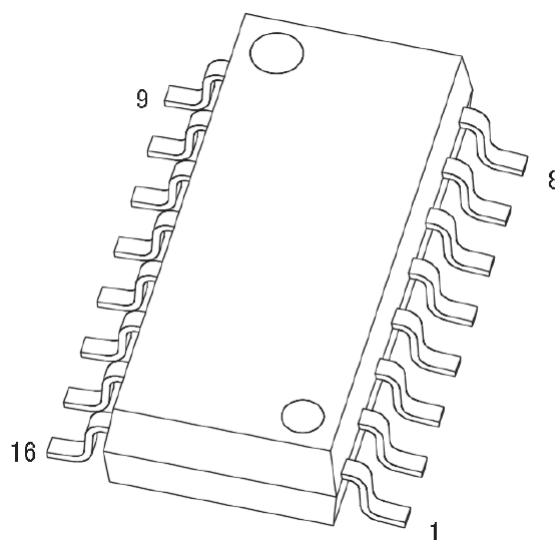
### SCHEMATIC

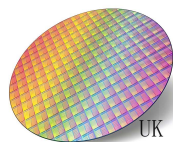


### PIN DEFINITION

**1,3,5,7 :** Cathode /Anode  
**2,4,6,8 :** Anode/Cathode  
**9,11,13,15:** Emitter  
**10,12,14,16:** Collector

### PACKAGE OUTLINE



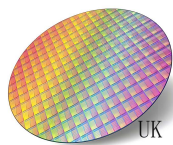


### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	$I_F$	$\pm 60$	mA	
Peak Forward Current	$I_{FP}$	$\pm 1$	A	1
Input Power Dissipation	$P_i$	100	mW	
OUTPUT				
Collector - Emitter Voltage	$V_{CEO}$	80	V	
Emitter - Collector Voltage	$V_{ECO}$	6	V	
Collector Current	$I_C$	50	mA	
Output Power Dissipation	$P_o$	150	mW	
COMMON				
Total Power Dissipation	$P_{tot}$	200	mW	
Isolation Voltage	$V_{iso}$	3750	V <sub>rms</sub>	2
Operating Temperature	$T_{opr}$	-55~110	°C	
Storage Temperature	$T_{stg}$	-55~125	°C	
Soldering Temperature	$T_{sol}$	260	°C	

Note 1. 100 $\mu$ s pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%

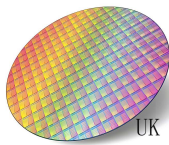


**ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C**

PARAMETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V <sub>F</sub>	-	-	1.4	V	IF=10mA	
Input Capacitance	C <sub>in</sub>	-	10	-	pF	V=0, f=1kHz	
OUTPUT							
Collector Dark Current	I <sub>CEO</sub>	-	-	100	nA	VCE=20V, IF=0	
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	80	-	-	V	IC=0.1mA, IF=0	
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	6	-	-	V	IE=0.1mA, IF=0	
TRANSFER CHARACTERISTICS							
Current Transfer Ratio	280-4	CTR	50	-	600	IF=1mA, VCE=5V	
	280-4GB		100	-	600		
CTR Symmetry		0.7	-	1.3		IF=±1mA, VCE=5V	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	-	0.07	0.2	V	IF=20mA, IC=1mA	
Isolation Resistance	R <sub>ISO</sub>	10 <sup>12</sup>	10 <sup>14</sup>	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C <sub>IO</sub>	-	0.4	1	pF	V=0, f=1MHz	
Response Time (Rise)	t <sub>r</sub>	-	7	18	μs	VCE=2V, IC=2mA RL=100Ω	3
Response Time (Fall)	t <sub>f</sub>	-	9	18	μs		3

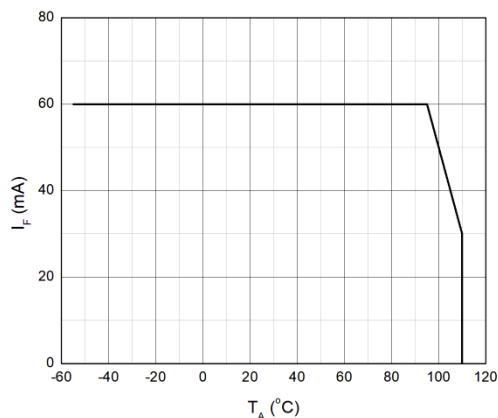
Note 3. Fig.12&13

Note 4. Fig.14

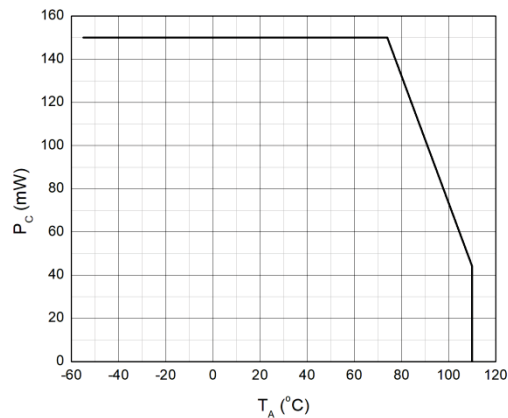


## CHARACTERISTIC CURVES

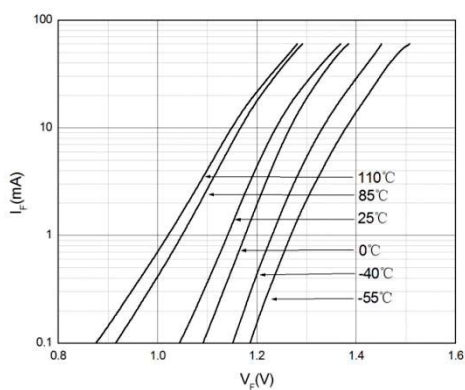
**Fig.1 Forward Current  
vs. Ambient Temperature**



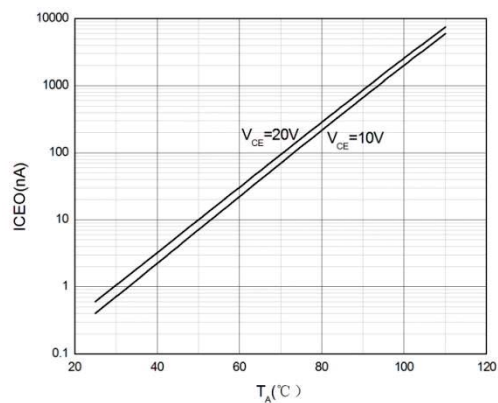
**Fig.2 Collector Power Dissipation  
vs. Ambient Temperature**



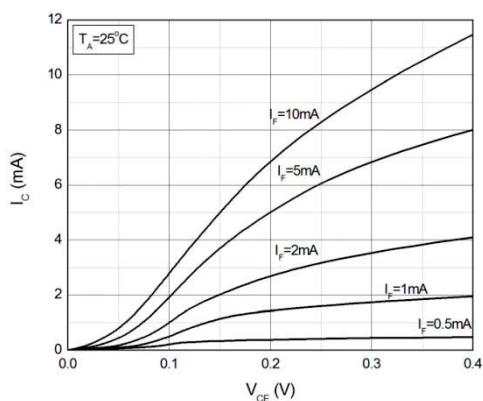
**Fig.3 Forward Current  
vs. Forward Voltage**



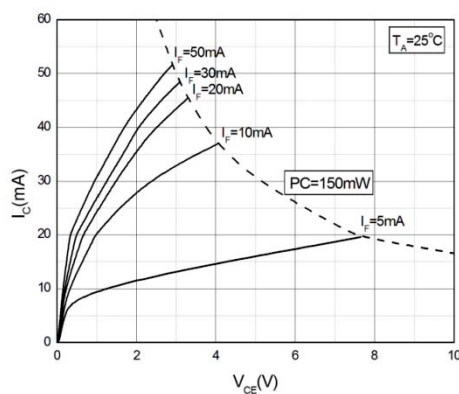
**Fig.4 Collector Dark Current  
vs. Ambient Temperature**

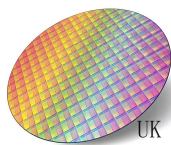


**Fig.5 Collector Current  
vs. Collector-emitter Voltage**



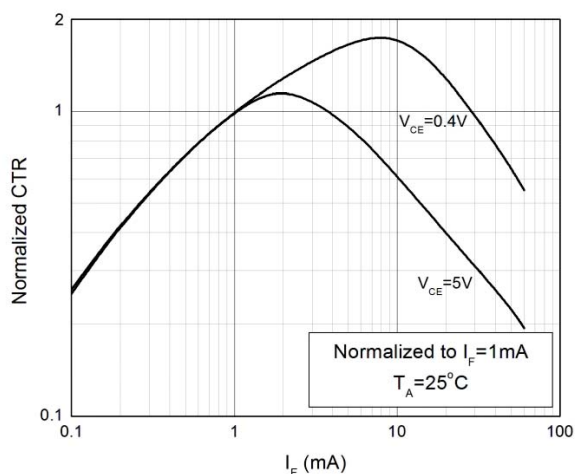
**Fig.6 Collector Current  
vs. Collector-emitter Voltage**



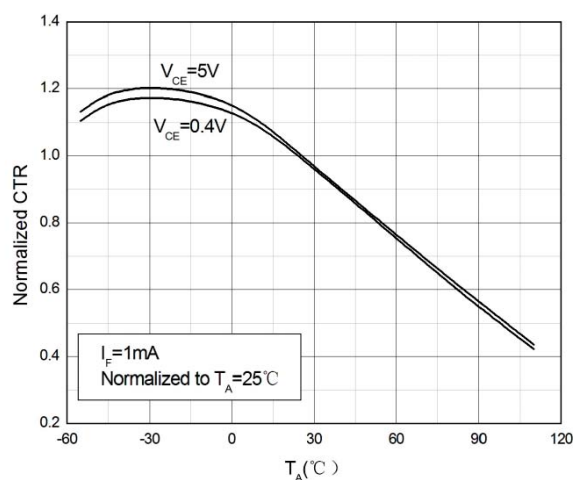


## CHARACTERISTIC CURVES

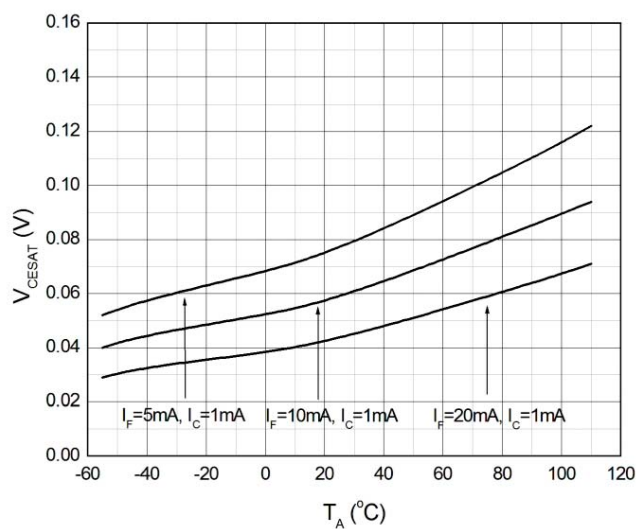
**Fig.7 Normalized Current Transfer Ratio vs. Forward Current**



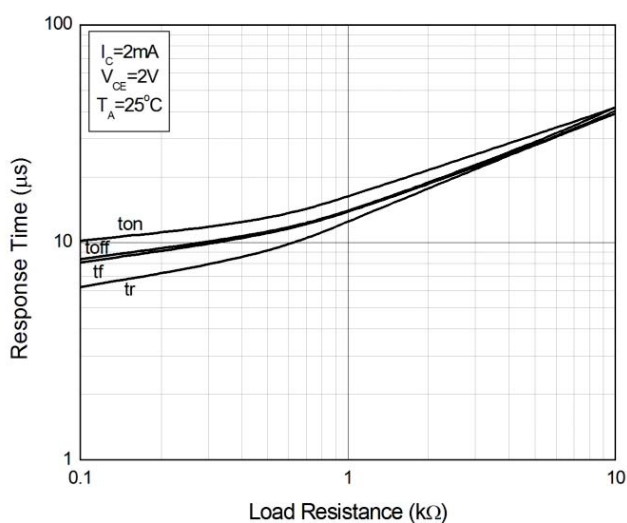
**Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature**



**Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature**



**Fig.10 Switching Time vs. Load Resistance**



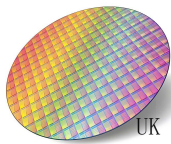
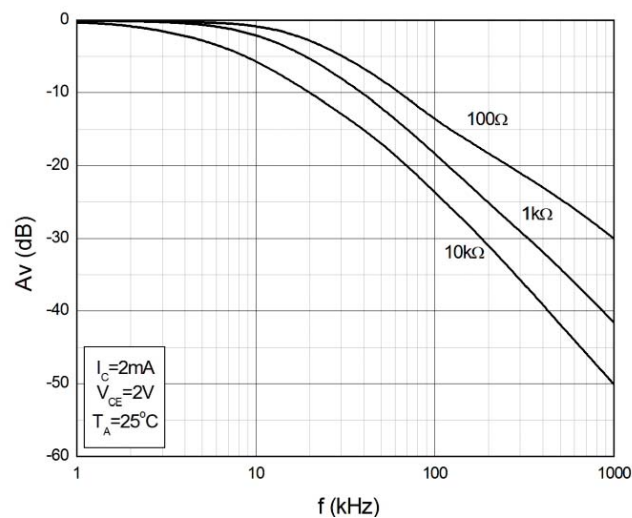


Fig.11 Frequency Response



## TEST CIRCUITS

Fig.12 Test Circuits of Response Time

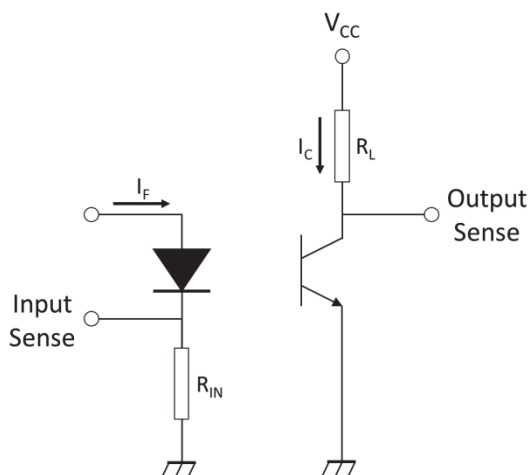


Fig.13 Curves of Response Time

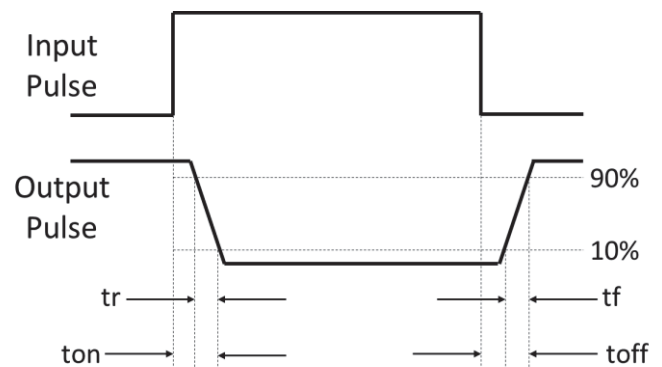
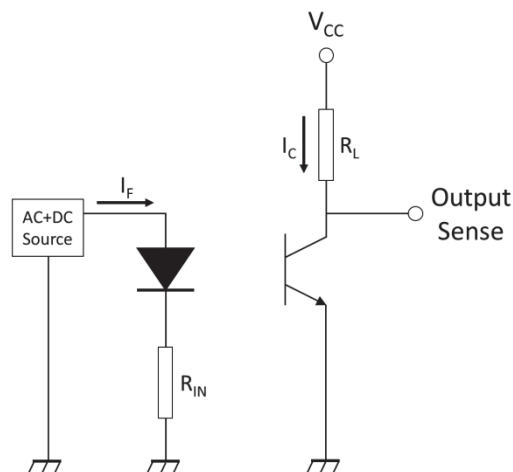
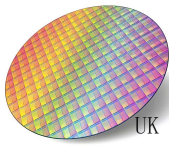
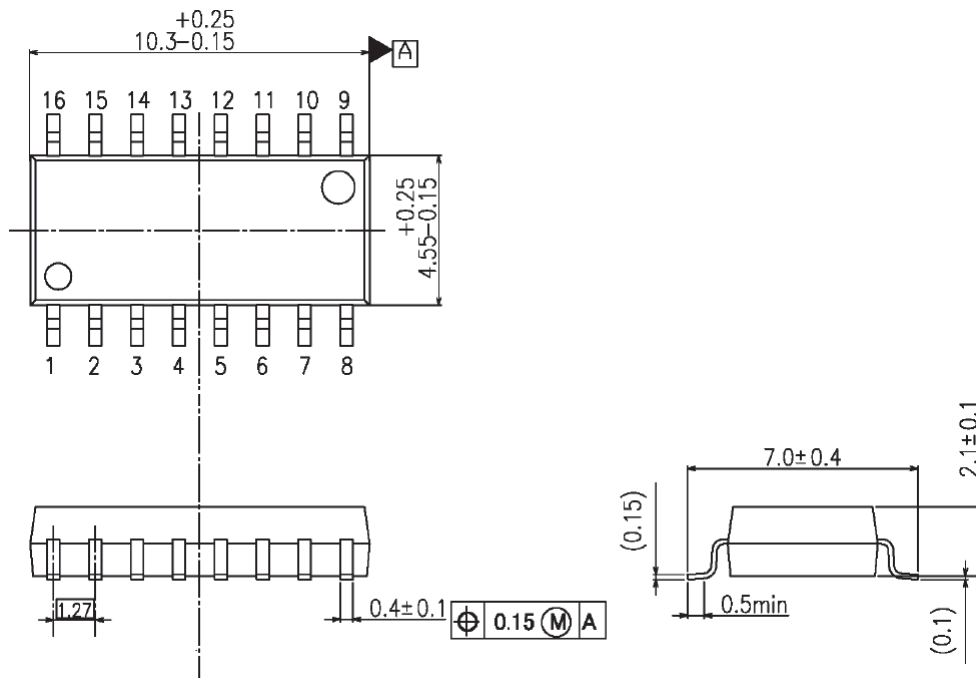


Fig.14 Test Circuits of Frequency Response

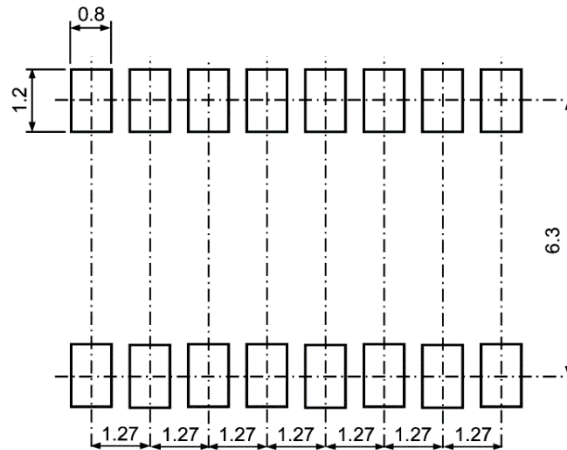


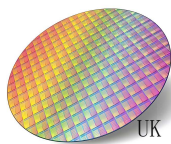


**PACKAGE DIMENSIONS** (Dimensions in mm unless otherwise stated)



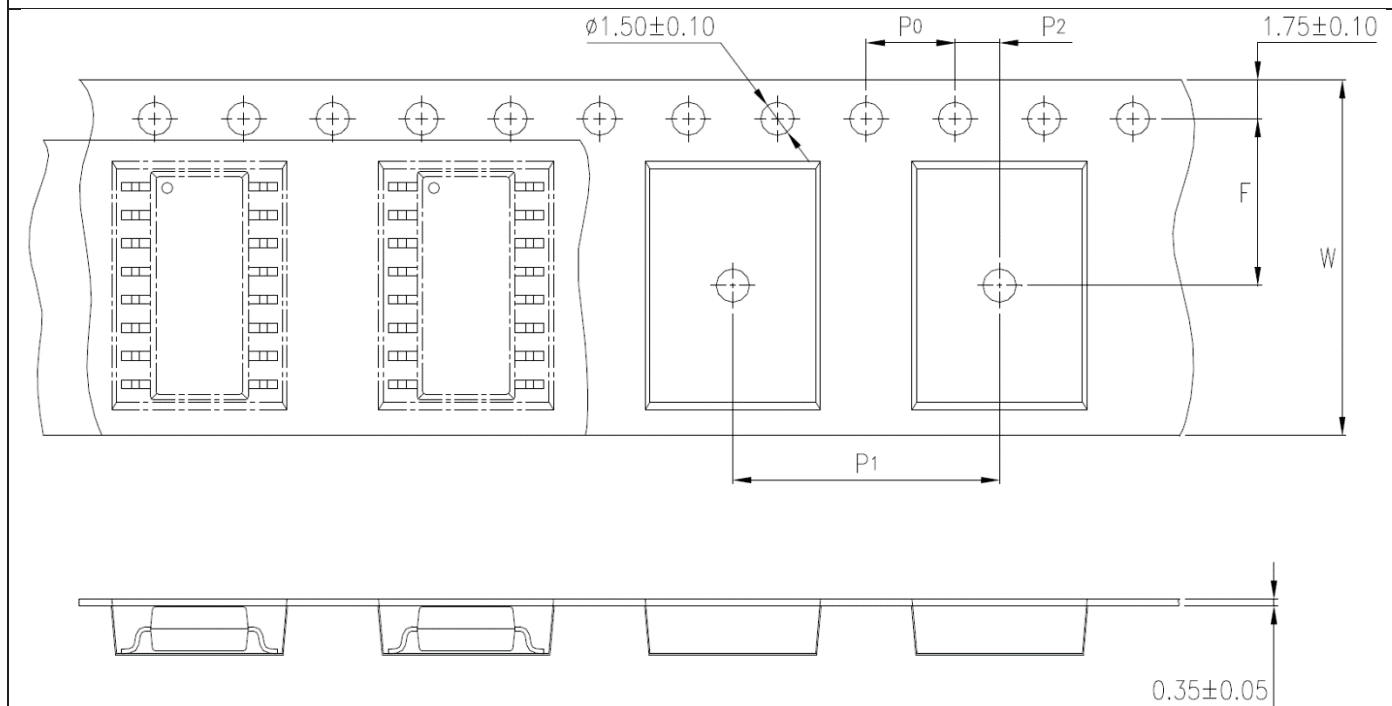
**Recommended Solder Mask** (Dimensions in mm unless otherwise stated)





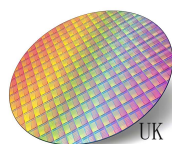
## CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

### Option T1



Description	Symbol	Dimension mm (inch)
Tape Width	W	$16 \pm 0.3$ (0.63)
Pitch of Sprocket Holes	P0	$4 \pm 0.1$ (0.15)
Distance of Compartment to Sprocket Holes	F	$7.5 \pm 0.1$ (0.295)
	P2	$2 \pm 0.1$ (0.079)
Distance of Compartment to Compartment	P1	$12 \pm 0.1$ (0.47)





## ORDERING AND MARKING INFORMATION

### MARKING INFORMATION



**AHP4** :Part Number

**/:** denotes Company Abbr.

**Y:** denotes 1 digit Year code, Y=Year  
(A-2010, B-2011, ... , K-2020, L-2021)

**WW:** denotes 2 digit Week code

### ORDERING INFORMATION

## IS280-4x

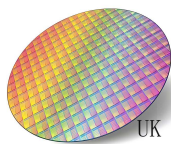
**IS** – Series Abbr.

**280-4** – Part Number

**X** – Rank (None/GB)

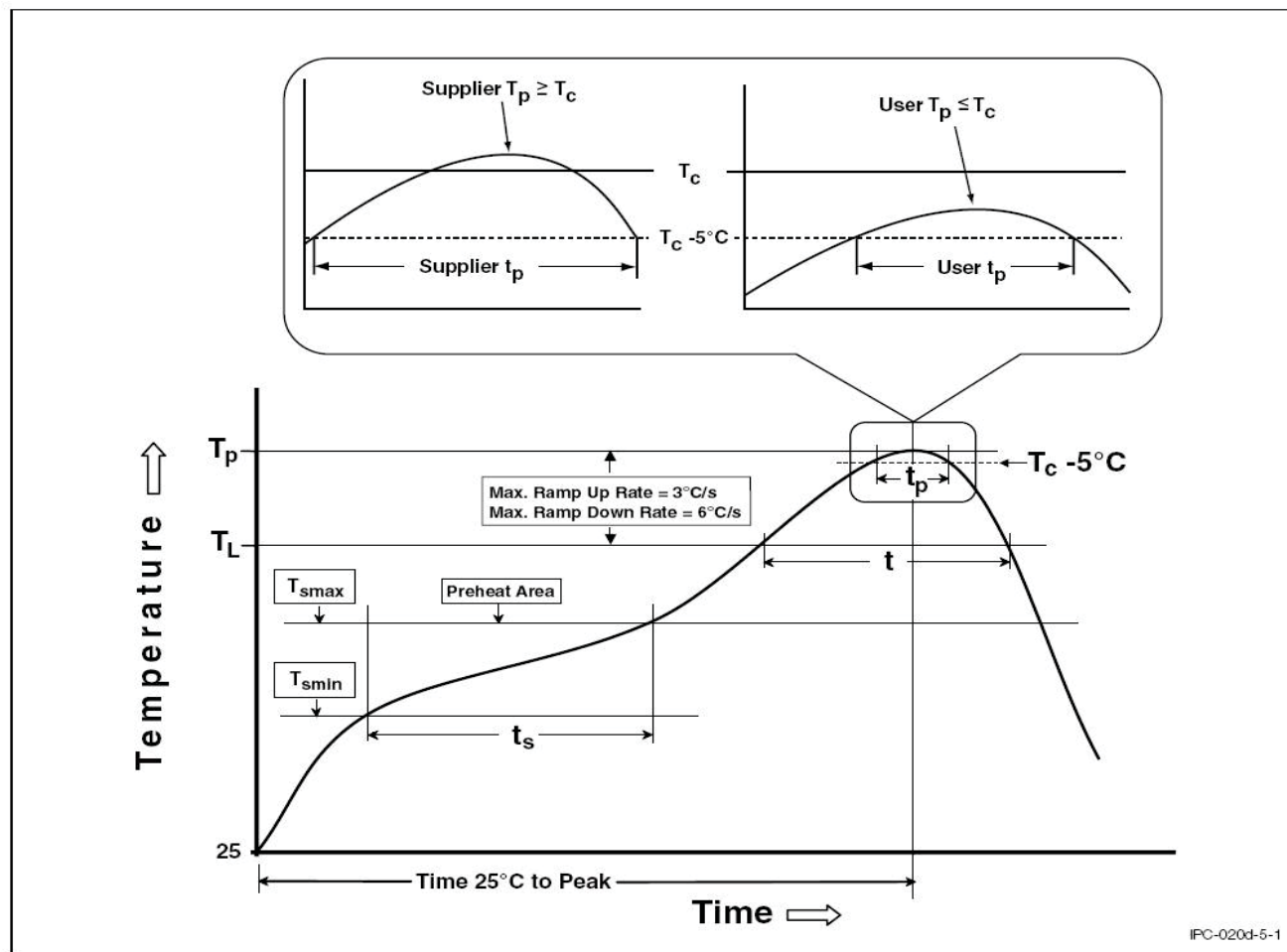
### PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	2000 Units/Reel	4 Reels/Inner box	5 Inner box/Outer box = 20k Units

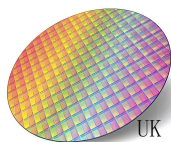


## REFLOW INFORMATION

### REFLOW PROFILE

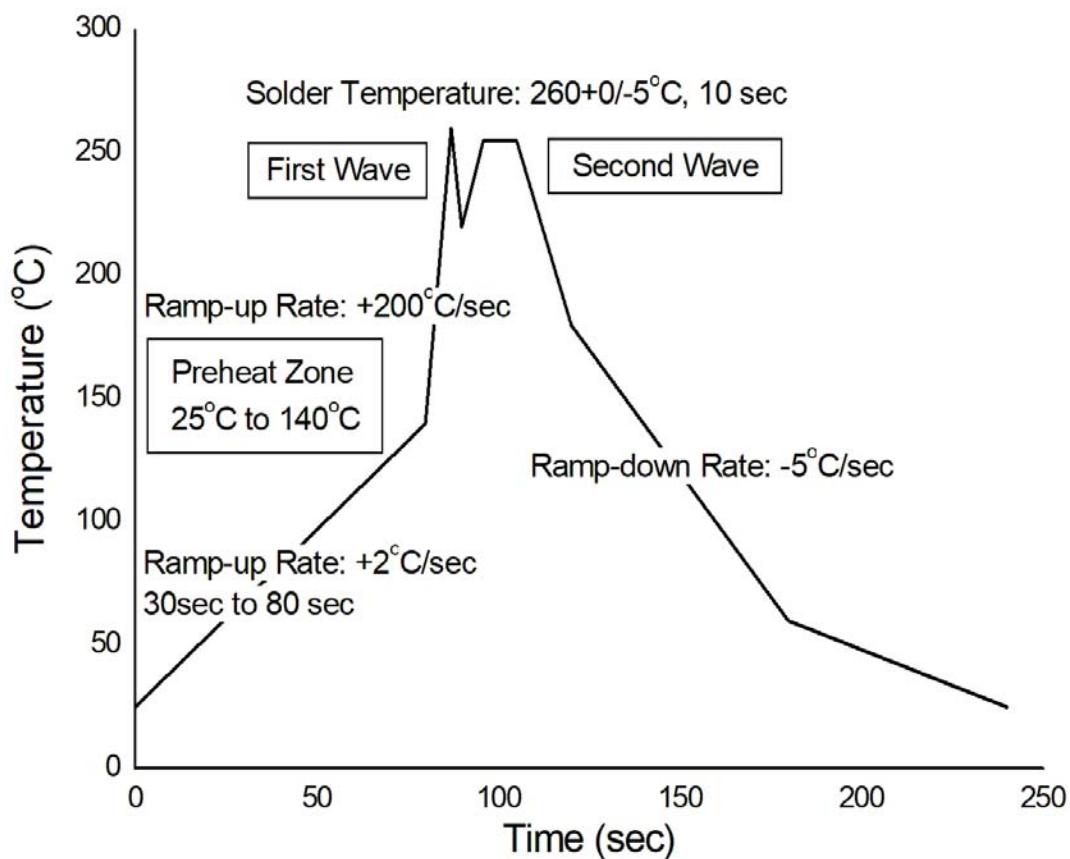


Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150°C
Temperature Max. (T <sub>smax</sub> )	150	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	183°C	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



## TEMPERATURE PROFILE OF SOLDERING

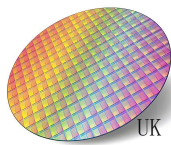
### WAVE SOLDERING (JESD22-A111 COMPLIANT)



### HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.



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Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It
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